

SmartLEWIS<sup>TM</sup> RX+

TDA5225

**Enhanced Sensitivity Multi-Configuration Receiver** 

Handling of Sensitivity

**Application Note** 

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Wireless Control

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**Overview and General Information** 

### 1 Overview and General Information

This document gives a simple overview on how to use the TDA5225 for best achievable sensitivity results.

For the TDA5225, the output signals DATA or DATA\_MATCHFIL can be used (transparent mode).

BER sensitivity measurements, as noted in the data sheet, use the transparent receive mode TMMF (DATA\_MATCHFIL output signal), where the received data is sampled with ideal data clock.

The DATA\_MATCHFIL output signal will provide higher systematic jitter than the DATA output signal.

Please keep in mind, that the achievable sensitivity in both transparent modes is significantly depending on the implemented clock and data recovery algorithm of the user software in the application controller.

For the sensitivity values given in the data sheet, also the filter settings in the signal chain (on-chip BPF and FSK PDF filter) are noted. In case these filter setting need to be adapted for the application, the achievable sensitivity will change accordingly.

## 2 TDA5225 Output Signals

There are two output sources of the matched filter shown in Figure 1:

- DATA: DC cancellation (Raw DATA Slicer) is applied to the 1-chip MF output
- DATA\_MATCHFIL: The signum is taken from the 2-chip MF output, no DC cancellation necessary

DATA\_MATCHFIL has about 3 dB better performance than DATA output, but DATA\_MATCHFIL output signal will provide higher systematic jitter than the DATA output signal (see different slopes of MF signal in **Figure 2**).

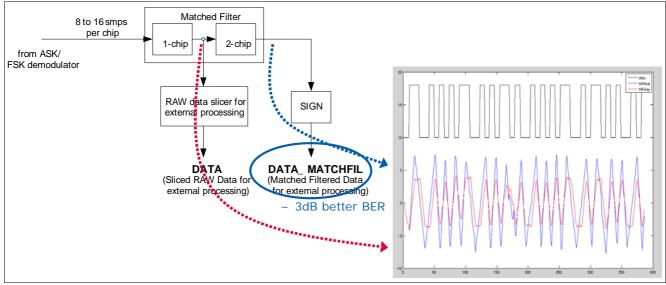


Figure 1 Matched Filter Output Sources

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**TDA5225 Output Signals** 

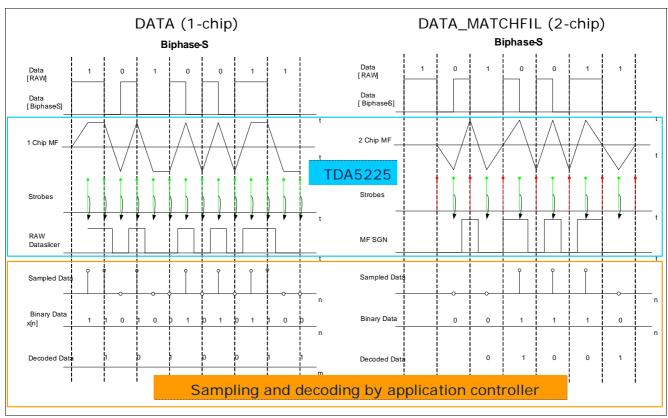


Figure 2 Matched Filter Output Signals

### 2.1 Output Signal DATA

A DC offset of the 1-chip MF signal must be compensated to be able to slice the data correctly.

This DC cancellation is based on a BW-adjustable digital lowpass filter. The bandwidth of the DC removal filter used for the Raw Data slicer (external slicer, register x\_EXTSLC) can be increased to achieve a faster settling time. Faster settling time comes at the cost of higher ripple which causes more jitter at the output.

NOTE: The ripple introduced by fast DC cancellation will also cause a decrease of performance.

The settling time does not only depend on the selected DC removal filter bandwidth but also on the frequency offset.

- In FSK a frequency offset introduces a DC offset at the output of the Matched Filter
- In ASK there is also a DC offset introduced due to the antilog function needed for linearization of the input signal

The preamble of the transmitted signal must be long enough for the filter to settle.



# TDA5225 Handling of Sensitivity

**Final Conclusion - Data Jitter** 

### 2.2 Output Signal DATA\_MATCHFIL

On usage of the 2-chip Matched Filter output, the DC cancellation is achieved within one symbol.

There is no ripple because of the DC cancellation, therefore the sensitivity is increased, but DATA\_MATCHFIL output signal will provide higher systematic jitter, due to different slopes of MF signal shown in **Figure 2**.

The "systematic jitter" is data-dependent and can therefore be compensated by the application controller.

### 3 Final Conclusion - Data Jitter

Three types of jitter are superimposed at the output and contribute differently at different input power levels:

- Systematic Jitter can be reduced by oversampling (TDA5225 Explorer software tool is generating the optimal chip-internal oversampling). This jitter can also be observed at good RF input power levels.
- Smaller DC canceller bandwidth (RAW Data Slicer) can be used to reduce ripple and therefore reduce the jitter slightly, but this increases the slicer settling time. For the final application a trade-off between settling time and ripple must be made.
- Jitter due to Noise can not be reduced (except for a BPF BW reduction) and limits therefore the achievable performance.

IMPORTANT NOTE: When the software clock-data recovery in the application controller requires an additional criterion of a certain allowed jitter at the output signal of the radio, the noted high sensitivity can NOT (not even under best case conditions) be achieved at the Raw Data Slicer output (DATA).

Usage of the 2-chip matched filter output (DATA\_MATCHFIL) and compensation for systematic pulse width "modulation" needs to be done in the external "high performance" software clock recovery, which may require a strong application controller.

Note: The TDA5235/40 can deliver high sensitivity due to internal available multi-bit signals (TDA5225 only delivers a 1-bit output signal) and a real hardware clock-recovery unit.

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